



PRODUCT SPECIFICATION

(產品規格書)

產品名稱 Description	產品料號 Part No.	圖號 Drawing No.
2244 Series P.C.B Socket 1.27mm	2244-1XxxG00SB	2244D02003
	2244-2XxxG00SB	2244D02004

PRODUCT NAME (產品名稱)	DOCUMENT No.: (文件編號)	Rev. (版本)	OUPIIN
2244 Series P.C.B Socket 1.27mm (RoHS)	Q2244-PSS-I001	B (I719)	(歐品)
	Approved (核准)	Checked (審核)	Prepared (製作)
	Q.A. Section Chief	Ruru Chen	2023.02.20



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1. SCOPE 適用範圍

This product specification defines the product performance and the test methods to ascertain the performance of the 2244 Series P.C.B Socket 1.27mm which is designed and manufactured by Oupiin Electronic Co., Ltd. This product specification is applicable but not only for those part numbers which be shown in the cover page.

本產品規格書規定了由歐品電子有限公司設計生產的 2244 Series P.C.B Socket 1.27mm 連接器產品的特性及測試方法。本產品規格書適用於但不局限於封面所顯示的產品料號

2. REFERENCE DOCUMENTS 參考文件

EIA364 Test method for electrical components 電子零件測試方法

3. FEATURE & DIMENSIONS 特徵及尺寸

3.1. PRODUCT DIMENSION 產品尺寸

These connectors shall have the dimensions as shown in drawing.
本產品的相關尺寸參見圖面

3.2. PCB/PANEL LAYOUT 印刷電路板佈局

The recommended PCB layout is shown in drawing.
本產品適用的 PCB layout 參見圖面

3.3. BILL OF MATERIAL 材料清單

Harmful material controlling follows the requirements of RoHS. The bill of material is described in drawing.
有害物質控制符合RoHS指令要求。本產品使用的材料參見圖面

3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC 機械及電氣特性

The connector shall have the mechanical and electrical performance as described in drawing.
本產品的機械及電氣特性參見圖面

3.5. PACKAGING 包裝

Products shall be packaged according to requirements specified in purchase order for safe delivery, connector container and the packaging method are shown in package specification.
產品可依客戶指定要求包裝，包裝材料與包裝方式參見產品包裝規範



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3.6. RATING CURRENT, RATING VOLTAGE 額定電流與額定電壓

Rating current : 1 A

額定電流 : 1 A

Rating voltage : 250V AC/DC

額定電壓 : 250V AC/DC

3.7. OPERATING TEMPERATURE 使用溫度

Temperature range : -40°C ~+105°C

使用溫度 : -40°C ~+105°C

4. ENVIRONMENTAL 環境要求

4.1. SOLDERABILITY 可焊性

Connectors meet solder-ability to EIA-364-52.and shall be free of contaminants.

產品可焊性符合 EIA-364-52. 標準規定的相關要求，表面不得有污染物

4.2. RESISTANCE TO SOLDER HEAT 耐焊接熱

4.2.1. INFRARED REFLOW 紅外線回流焊接

Each cycle consists of three consecutive phases. as shown in Table II..

每個焊接週期包括三個連續的階段，見附表二

Note: 說明

Device temperature measurements are referenced from the top-center of the package outer surface.

設備溫度量測時以從頂部中間位置測量為準。

5. PERFORMANCE AND TEST DESCRIPTION 性能及測試

5.1. REQUIREMENT 要求

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I.**

本產品設計符合附表一所列的機械，電氣及環境要求

5.2. TEST CONDITION 測試條件

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

除非特別註明，所有測試在室溫條件下完成



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5.3. SAMPLE SELECTION 樣品選擇

Test samples shall be selected at random from current production. No test samples shall be reused. Samples are pre-conditioned with 10 cycles of durability. Each group shall be containing 5 test samples at least.

測試樣品從現生產的產品中隨機抽取，所有測試過的樣品不得重複使用。樣品已預先插拔10次，每組測試至少有5個樣品



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Table I : Test Requirements and Procedures

附表一：測試要求

Items (項目)	Requirements (要求)	Test Methods (檢測方法)
1. Confirmation of Product 產品確認	Product shall be conforming to the requirements of applicable product drawing. 產品必須滿足相關檔的規定	Visually, dimensions and functionally inspected per applicable product drawing. 依相關產品圖面，檢查產品的外觀、尺寸及功能
2. Contact Resistance 接觸阻抗	20mΩ Max 最大 20mΩ	Subject mated contacts assembled in housing to 20mV DC max open circuit at 10mA max. Per EIA-364-23 測試最大電流 10 mA，最大電壓 20 mV 適用：EIA-364-23
3. Insulation Resistance 絕緣阻抗	1000 MΩ Min. 最小 1000 MΩ.	Test between adjacent contacts of mated and unmated connector assemblies. (500V DC) Per EIA-364-21 在連接器組件的相鄰端子之間進行測試 (500V DC) 適用：EIA-364-21
4. Dielectric Withstanding Voltage 耐電壓	After testing, no breakdown or flashover shall occur. 測試後，產品無損壞且不得發生閃絡	Connector must withstand test potential of 300 V AC for 1 minute. Per EIA-364-20 樣品必須承受測試電壓 300V AC，時間一分鐘， 適用：EIA-364-20.
5. Mating/ Un-mating Force 插入力/拔出力	Mating force : 2N/Pin max. Un-mating force : 0.3N/Pin min. 插入力最大 2N/Pin 拔出力最小 0.3N/Pin	At a speed of 24.5 mm/minute, apply axial insert the mating part into fully or pull out from the subject product. Per EIA-364-13 以 24.5mm/分鐘的速度，軸向完全插入對配外掛程式到被測產品中或從被測產品中拔出 適用：EIA-364-13



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<p>6. Durability 耐久性</p>	<p>After testing, no physical damage. Contact Resistance 30 mΩ Max. 測試後，產品外觀無損壞，接觸阻抗最大30 mΩ</p>	<p>Repeat mate and unmated for connector 100 cycles, at a speed of 24.5 mm/minute. Per EIA-364-09 重復進行配合產品 100 次插拔，以 24.5mm/分鐘的速度 適用：EIA-364-09</p>
<p>7. Thermal Shock 溫度沖擊</p>	<p>After testing, no physical damage. Contact Resistance 30 mΩ Max. 測試後，產品外觀無損壞，接觸阻抗最大30 mΩ</p>	<p>Temperature range from -40°C to +105°C. Start from -40°C, after 30 minutes, change to +105°C; total 5 cycles. Per EIA-364-32. 溫度變化範圍：-40°C ~ +105°C。從 -40°C 開始，30 分鐘後換到+105°C，共 5 個循環 適用：EIA-364-32</p>
<p>8. High Temperature Life 高溫老化</p>	<p>After testing, no physical damage. Contact Resistance 30 mΩ Max. 測試後，產品外觀無損壞，接觸阻抗最大30 mΩ</p>	<p>Subject product to 105°C for 96 hours continuously. Per EIA-364-17 產品置於 105°C，連續 96 小時 適用：EIA-364-17</p>
<p>9. Humidity 恆溫恆濕</p>	<p>After testing, no physical damage. Contact Resistance 30 mΩ Max. Dielectric Strength should be OK, Insulation Resistance should be 500 MΩ min. 測試後，產品外觀無損壞，接觸阻抗最大 30 mΩ；耐電壓測試 OK，絕緣阻抗 500MΩ 最小</p>	<p>Temperature : 40±2°C Relative Humidity : 90-95%; Duration : 96 Hours. Per EIA-364-31 溫度：40±2°C 相對濕度：90-95% 時間：96 小時 適用：EIA-364-31</p>
<p>10. Salt Spray 鹽霧</p>	<p>After testing, no physical damage. Contact Resistance 30 mΩ Max. Dielectric Strength should be OK, Insulation Resistance should be 500 MΩ min. 測試後，產品外觀無損壞，接觸阻抗最大 30 mΩ；耐電壓測試 OK，絕緣阻抗 500MΩ 最小</p>	<p>5±1% salt concentration, 16 hours, 35±2°C Per EIA-364-26 鹽水濃度(重量比)5±1%，時間 16 小時，溫度 35±2°C 適用：EIA-364-26</p>



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11. Solder ability 可焊性	There shall have a solder coverage of 95% minimum. 產品在測試完成後，焊接部位粘錫面積大於95%。	Soldering time : 3-5 Seconds Soldering Temperature : 245±5°C Per EIA-364-52. 焊接時間：3-5 秒 焊接溫度：245±5°C 適用：EIA-364-52
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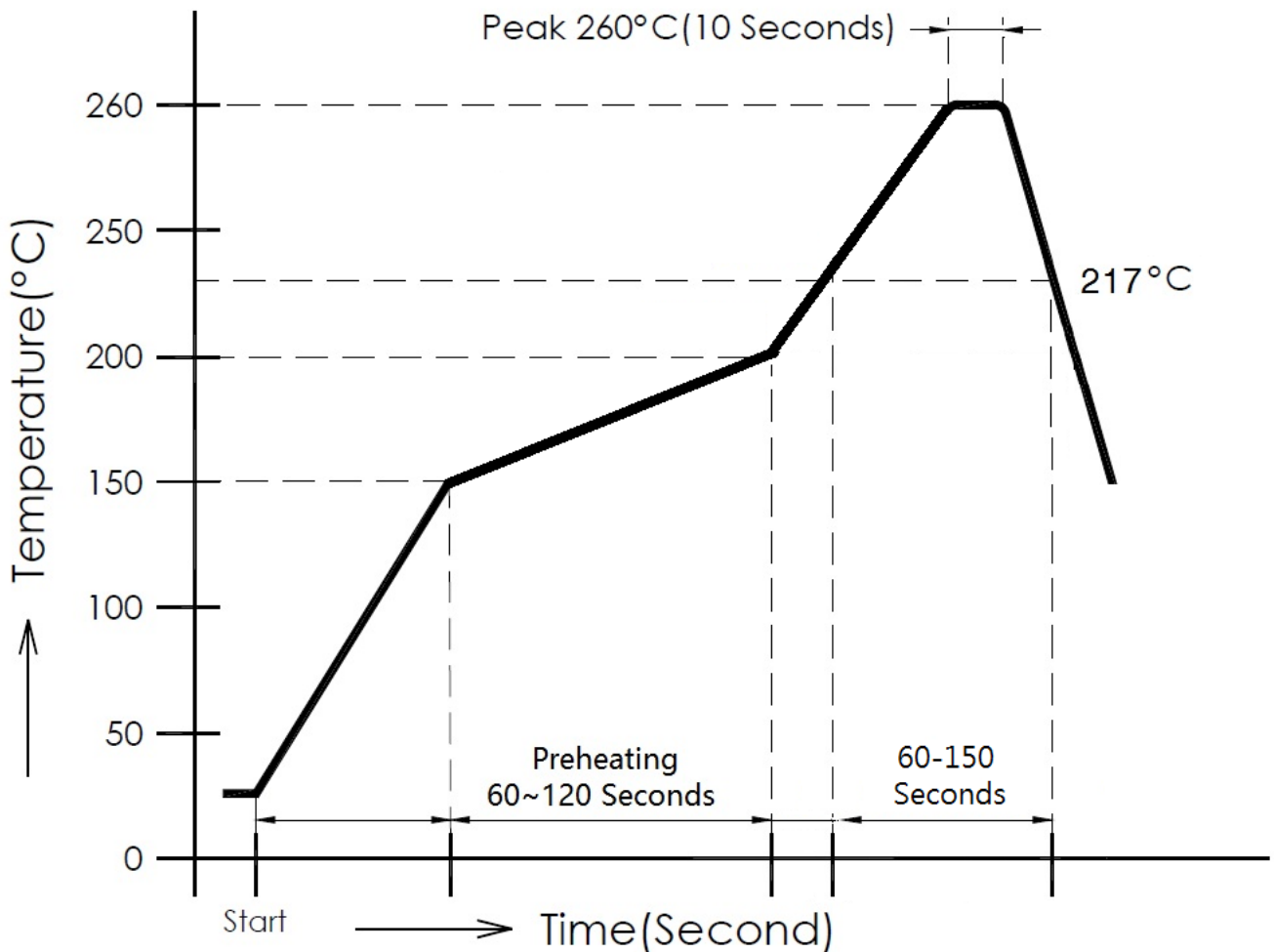


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Table II : Reflow Soldering Profile

附表二：回流焊曲線圖

Parameter 參數	Reference 參考	Specification 規格
Ramp-up (升溫區)	25°C ~150°C	3°C /S Max
Pre-heating (預熱區)	150°C ~200°C	60~120 sec
Time maintained above(保持時間)	217°C	60-150 sec
Peak Temperature	260+0/-5°C	10 sec



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile largely dependent on the reflow equipment.

這個曲線圖是評估元件器件焊接抗熱的基本要求，應用在對焊接中的熱傳遞方式是熱氣對流，達到特定曲線圖地實際溫度主要依賴與回流焊接設備